T-Flash SOCKETS

技术参数 / Technical parameter

PIN 数(Number of contacts)：8PIN	耐电压(Withstand voltage)：500V AC for 1 min
操作方式(Operation mode)：翻盖式/HINGE	操作寿命(Operation life)：5,000 Cycles Min
温度范围(Operating temp)：-40℃ TO +80℃	焊接温度(Welding temperature)：260±5° 5s
额定负荷(Rated load)：0.5A PERP IN.	焊接方式(Welding mode)：贴片式/SMT
接触电阻(Contact resistance)：100mΩ max.	包装方式(Packaging method)：卷带/Tape & Reel (TR)
绝缘电阻(Insulation resistance)：1000MΩ min.	最小包装(Minimum packing)：1,500/PCS

TF-102-ARP8H16
W13.40xD13.56xH1.60

外形尺寸(UNIT:MM) / Size Chart

更多资料请参考技术选型档！

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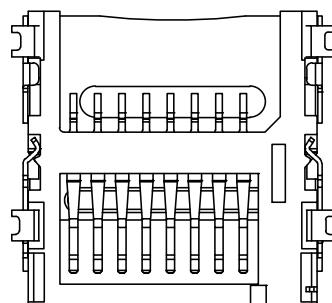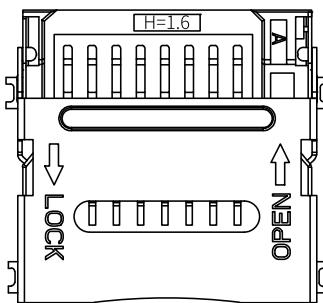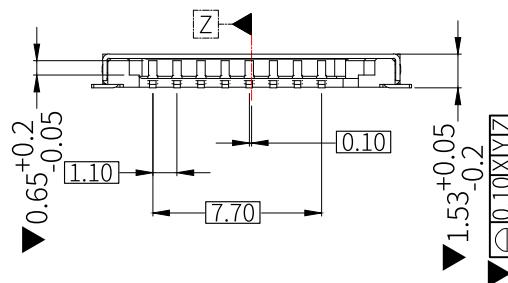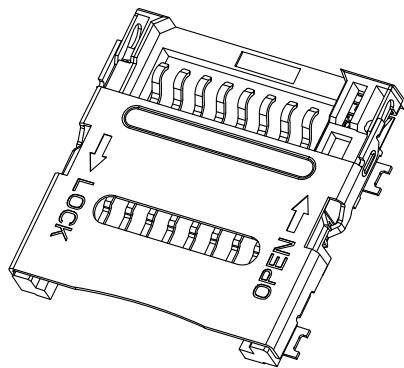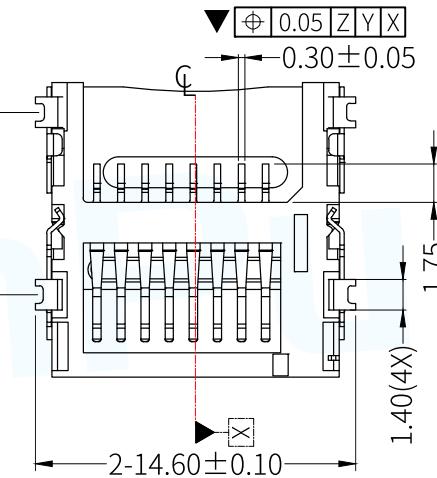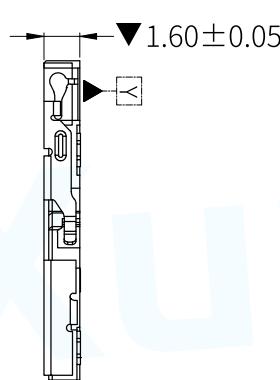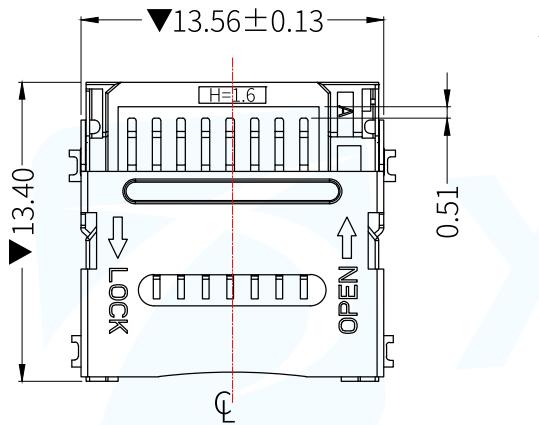
NOTES

1.FINISH：
　　Contact：Au 1u" Plating On Contact Area,
　　　　　　100~200u" Sn Plating On Solder Tails,
　　　　　　50u" Nickel Underplating Voer All.
　　Shell：No Plating.

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线路板安装(UNIT:MM) / Mounting Dimensions

0.80(8X)

C8 C7 C6 C5 C4 C3 C2 C1
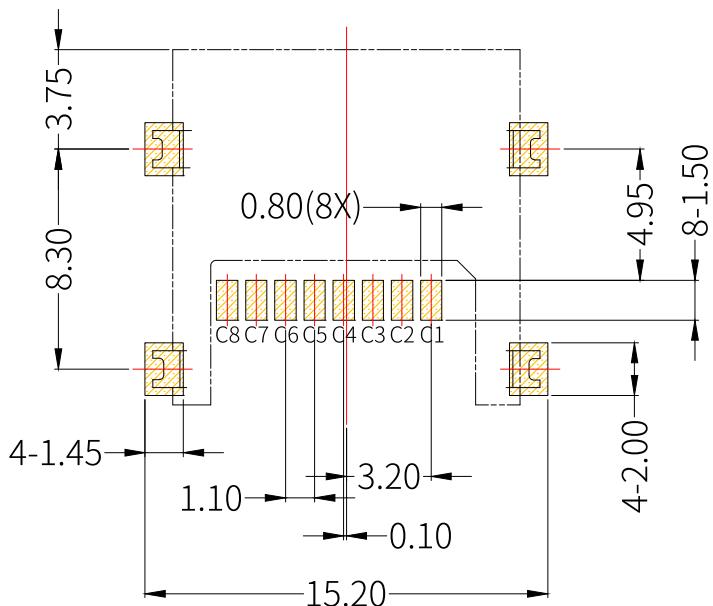
PCB焊盘区(PAD AREA)

禁区(KEEP OUT AREA)

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

● T-Flash CARD

1 2 3 4 5 6 7 8

T-Flash CARD
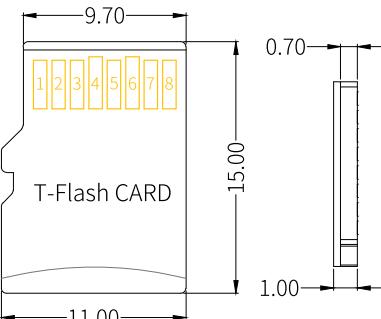
● 引脚定义/Pin Definition

PIN#	NAME	TYPE	DESCRIPTION
C1	DAT2	I/O/PP	DATE LIN(BIT2)
C2	CD/DAT3	I/O/PP	CARD DETECT DATELIN(BIT3)
C3	CMD	PP	COMMAND RESPONSE
C4	VDD	S	SUPPLY VOLTAGE
C5	CLX	I	CLOCK
C6	VSS	S	SUPPLY VOLTAGE GROUND
C7	DAT0	I/O/PP	DATE LIN(BIT0)
C8	DAT1	I/O/PP	DATE LIN(BIT1)

焊接条件 / Welding conditions

● 回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products

温度分布/Temperature distribution
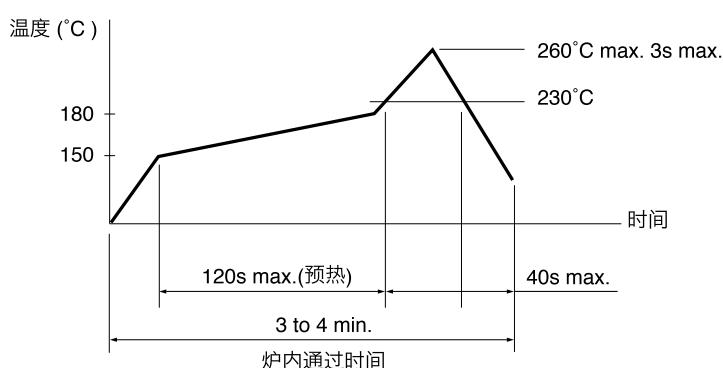
● 手焊式/Hand welding

项目/Project	条件/condition
焊接温度 Welding temperature	350°C max.
持续焊接时间 Continuous welding time	3s max.
焊剂斗容量 Flux bucket capacity	60W max.

● 浸焊式/Immersion soldering

项目/Project	条件/condition
助焊剂附着量 Flux adhesion	不附着于零部件贴装面的程度 Not attached to the mounting surface of components
预热温度 Preheating temperature	印刷电路板焊接面的周围温度 100°C max. The temperature around the welding surface of PCB is 100 °C max
预热温度时间 Preheat temperature time	60s max.
焊接温度 welding temperature	260°C max.
焊接浸渍时间 Welding immersion time	5s max.
焊接次数 Welding times	2 times max.

注:

1. 加热方式:以远红外线上下加热方式。
2. 温度测量:用Φ0.1~0.2 的 CA(K)或 CC(T)测量位置在焊接连接部(锡/铜箔面)。
3. 固定方式:采用耐热胶带。